

# SANYO Semiconductors

DATA SHEET

An ON Semiconductor Company



# N-Channel Silicon MOSFET ECH8662 — General-Purpose Switching Device **Applications**

# **Features**

- Low ON-resistance
- 2.5V drive
- · Halogen free compliance
- Protection diode in

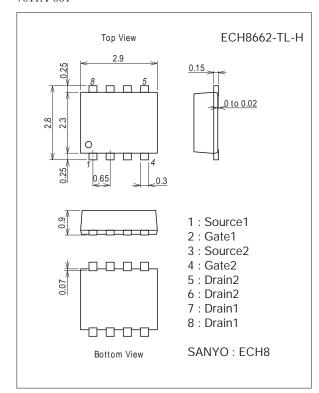
# **Specifications**

#### Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	VDSS		40	V
Gate-to-Source Voltage	VGSS		±10	V
Drain Current (DC)	ID		6.5	А
Drain Current (Pulse)	IDP	PW≤10μs, duty cycle≤1%	40	А
Allowable Power Dissipation	PD	When mounted on ceramic substrate (900mm <sup>2</sup> ×0.8mm) 1unit	1.3	W
Total Dissipation	PT	When mounted on ceramic substrate (900mm <sup>2</sup> ×0.8mm)	1.5	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

## Package Dimensions

unit : mm (typ) 7011A-001



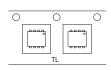
#### **Product & Package Information**

 Package : ECH8

- JEITA, JEDEC
- Minimum Packing Quantity : 3,000 pcs./reel

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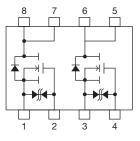
#### Packing Type : TL



#### Marking



#### **Electrical Connection**

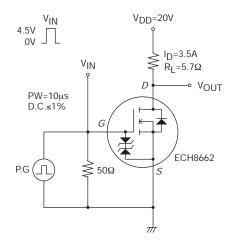


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# Electrical Characteristics at Ta=25°C

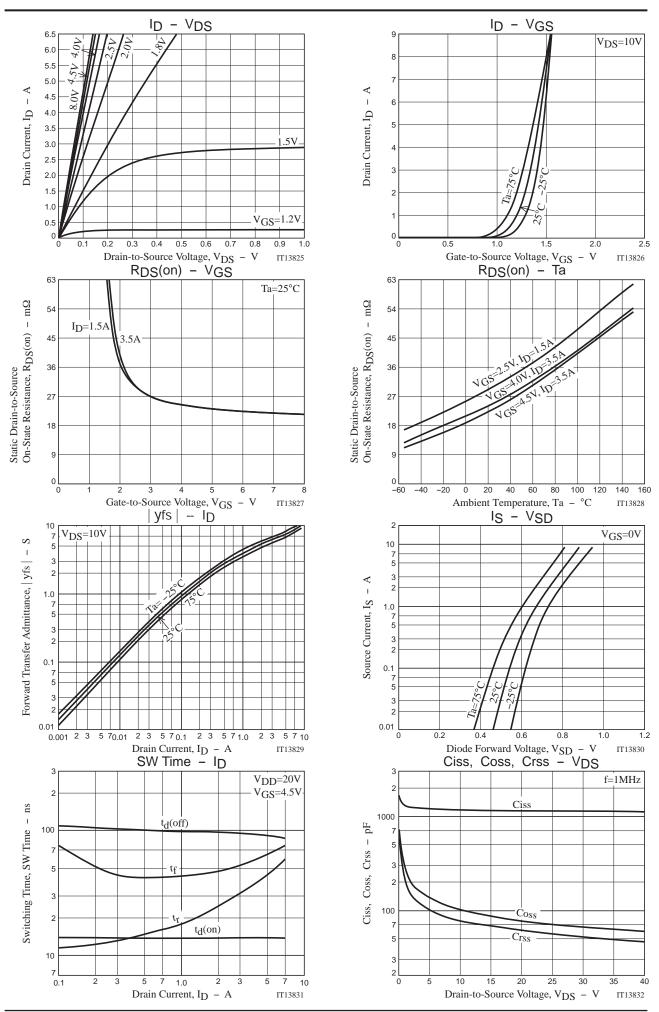
Decemeter	Cumbral			Ratings			
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=1mA, VGS=0V	40			V	
Zero-Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V			1	μΑ	
Gate-to-Source Leakage Current	IGSS	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V			±10	μΑ	
Cutoff Voltage	V <sub>GS</sub> (off)	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA	0.4		1.3	V	
Forward Transfer Admittance   yfs		V <sub>DS</sub> =10V, I <sub>D</sub> =3.5A 3.		6.5		S	
	R <sub>DS</sub> (on)1	ID=3.5A, VGS=4.5V			30	mΩ	
Static Drain-to-Source On-State Resistance	R <sub>DS</sub> (on)2	ID=3.5A, VGS=4V		25	33	mΩ	
	R <sub>DS</sub> (on)3	ID=1.5A, VGS=2.5V			42	mΩ	
Input Capacitance	Ciss	VDS=20V, f=1MHz		1130		рF	
Output Capacitance	Coss	VDS=20V, f=1MHz		77		рF	
Reverse Transfer Capacitance	Crss	V <sub>DS</sub> =20V, f=1MHz		60		pF	
Turn-ON Delay Time	t <sub>d</sub> (on)			14		ns	
Rise Time	tr			34		ns	
Turn-OFF Delay Time	t <sub>d</sub> (off)	See specified Test Circuit.		93		ns	
Fall Time	tf			55		ns	
Total Gate Charge	Qg			12		nC	
Gate-to-Source Charge	Qgs	V <sub>DS</sub> =20V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =6.5A		2.2		nC	
Gate-to-Drain "Miller" Charge	Qgd	1		3.4		nC	
Diode Forward Voltage	VSD	IS=6.5A, VGS=0V		0.85	1.2	V	

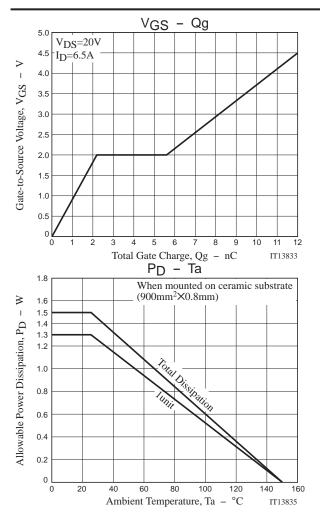
# Switching Time Test Circuit

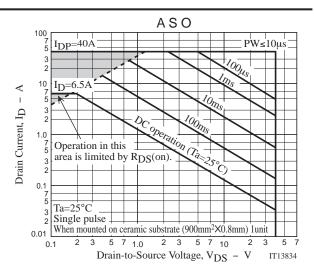


## **Ordering Information**

Device	Device Package		memo	
ECH8662-TL-H ECH8		3,000pcs./reel	Pb Free and Halogen Free	







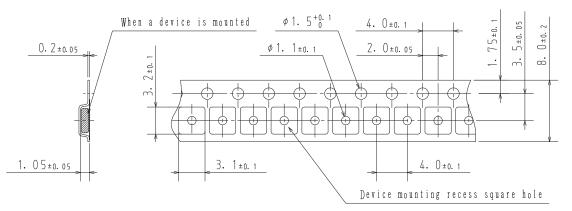
### Embossed Taping Specification ECH8662-TL-H

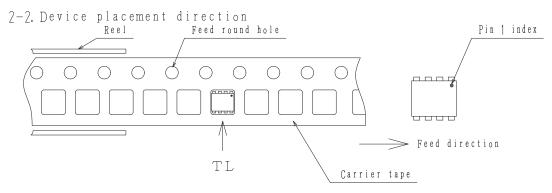
1. Packing Format

Package Name	Carrier Tape Maximum Numbe devices contain			Packing format	
	Туре	Reel	Inner box	Outer box	Inner BOX (C-1) Outer BOX (A-7)
ECH8	CPH6	3,000	15,000	90,000	5 reels contained 6 inner boxes contained
_	_				Dimensions:mm (external) Dimensions:mm (external)
					183×72×185 440×195×210
Packing method Reel label, Inner box label (unit:mm) Outer box label It is a label at the time of factory sh The form of a label my change in physic distribution process.   Type No. LOT No. Quantity 69 108   Origin 108 108   Worte (1) 000000000 1000   NOTE (1) The LEAD FREE * description shows that the surface treatment of the terminal is lead free.   Label JEITA Phase   LeAD FREE 4 JEITA Phase					

2. Taping configuration

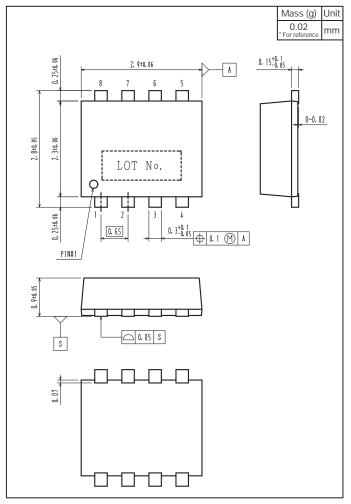
2-1. Carrier tape size (unit:mm)



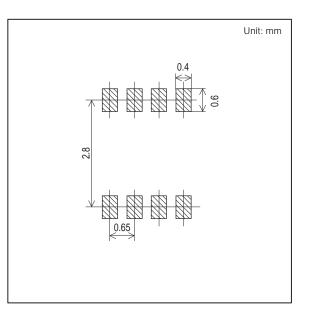


Those with pin 1 index on the feed hole side·····TL

# Outline Drawing ECH8662-TL-H



Land Pattern Example



Note on usage : Since the ECH8662 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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